

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended): A large-dimension image sensor operating by relative translation of the image with respect to the sensor, comprising _:

a plurality of individual monolithic chips (~~P1, P2, P3~~) each capable of detecting a linear image portion perpendicular to the translation direction $[(Ox)]$, the individual chips being arranged in a first group and a second two groups, the chips ~~of one~~ group being aligned the first group in order to detect aligned image portions and the chips of the ~~other~~ second group being aligned in order to detect other image portions which are aligned but offset with respect to the chips of the first group in the relative translation direction, the chips of the second group being arranged in a staggered fashion with respect to the chips of the first group so that all the chips of the first group lie beside at least one chip of the second group, each of the chips ~~each~~ being mounted on a package, connection wires being connected between connection terminals of the package and connection terminals on the upper surface of each of the chips, ~~characterized in that wherein~~ the upper surface of the package, on which the chip is mounted, comprises a principal part the shape of which is an elongate rectangle whose length is less than the length of the chip and whose width is greater than that of the chip, all of the connection terminals of the package $[(34)]$ lying inside this rectangle along the chip, all the chips having two ends protruding from the rectangle, a protruding end of a chip being adjacent, via a side parallel to the row of chips, to a side likewise parallel to the row of chips of the protruding edge of another chip, the packages being identical and juxtaposed without reversal.

2. (currently amended): The image sensor as claimed in claim 1, ~~characterized in that wherein~~ the package comprises two extensions (~~30, 32~~) adjacent to the rectangular principal part, this extension extending under the protruding chip part.

3. (currently amended): The image sensor as claimed in claim 2, ~~characterized in that~~ wherein the extensions are slightly wider and longer than this protruding chip part under which they lie.

4. (currently amended): The image sensor as claimed in claim 3, ~~characterized in that~~ wherein the width of the extension of the package is from about 50 micrometers to 200 micrometers more than the width of the chip.

5. (currently amended): An image sensor comprising a plurality of linear image detection arrays associated in order to form a linear image sensor with a length greater than that of each array, ~~characterized in that~~ wherein the arrays (~~P1, P2, P3~~) are mounted on packages (~~B1, B2, B3~~) whose upper surface has an elongate rectangular shape provided on two opposite sides of the rectangle (~~24, 26~~) with two extensions (~~30, 32~~) substantially covered by the ends of the array, two packages being adjacent via a respective extension of each of them, no connection terminal being present on the packages in the region of the extensions, and the packages being identical and juxtaposed without reversal.